



APPLICATION SPECIALIST TRAINING COURSE EVALUATION IPC'S REWORK AND REPAIR TRAINING RECERTIFICATION PROGRAM

This form will be used to improve the quality of future courses. Your frank comments are welcomed.

1. Overall, was the course a valuable learning experience? (circle one)

No										Very much so
1	2	3	4	5	6	7	8	9	10	

Comments:

2. Did the course meet its stated objective? (circle one)

No										Very much so
1	2	3	4	5	6	7	8	9	10	

Comments:

3. What do you consider to be the main strengths of the course?

4. What do you consider to be the main weaknesses of the course as presented?

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5. Based on the class presentations, use the following scale to evaluate the modules listed below (where applicable for the modules taught)

Below Average

Above Average

1 2 3 4 5 6 7 8 9 10

- ____ 1. Common Procedures
- ____ 2. Wire Splicing
- ____ 3. Through Hole Components
- ____ 4. Chip and MELF Rework
- ____ 5. SOIC/SOT Rework
- ____ 6. J-Lead and QFP Rework
- ____ 7. Circuit Repair
- ____ 8. Laminate Repair
- ____ 9. Conformal Coating

6. Do you feel, based on the presentations in the class, that you have a more thorough understanding of the subjects listed above? (circle one)

(YES)

(NO)

7. Did you find the trainer's presentation to be clear and effective? (circle one:)

Not Effective

Extremely Effective

1 2 3 4 5 6 7 8 9 10

8. Would you recommend this course to your (circle one)

- Peers (YES) (NO)
- Subordinates (YES) (NO)
- Supervisor (YES) (NO)

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7
7
1
1

I
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7
2
1